	Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D ***: Required Field***

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	2014-05-20
Contact Name *	Refer to " Supplier Comment" section	**Contact Title**	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	**Contact Email ***	Refer to " Supplier Comment" section
Authorized Representative *	Laurent TOSI	**Representative Title**	MMS MD CHAMPION
Representative Phone *	33 442 685 795	**Representative Email ***	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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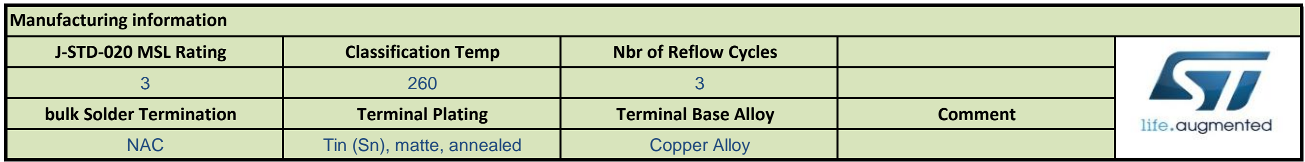
Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STM8S105K4U6A	H1MG*766XXXX	A	996C	2014-05-20
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	90.00	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		life.augmented
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	5x5x0.55	32	L bend	
Comment	UFQFPN 5X5X0.55 32L 0.5 MM PITCH			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**

QueryList : REACH-16th December 2013				
Query				**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						**Mfr Item Name**	**H1MG*766XXXX**					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
die (s)	Other inorganic materials	1.893	mg	supplier	die	Silicon (Si)	7440-21-3		1.745	mg	921817	19389
die (s)	Other inorganic materials	0.000	mg	supplier	metallization	Aluminium (Al)	7429-90-5		0.012	mg	6339	133
die (s)	Other inorganic materials	0.000	mg	supplier	metallization	Copper (Cu)	7440-50-8		0.052	mg	27470	578
die (s)	Other inorganic materials	0.000	mg	supplier	metallization	Tantalum (Ta)	7440-25-7		0.002	mg	1057	22
die (s)	Other inorganic materials	0.000	mg	supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	3170	67
die (s)	Other inorganic materials	0.000	mg	supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.011	mg	5811	122
die (s)	Other inorganic materials	0.000	mg	supplier	passivation	Indium Tin oxide (In203:SnO2)	50926-11-9		0.065	mg	34337	722
Die Attach Epoxy (Ablebond 8290)	Other inorganic materials	0.343	mg	supplier	Glue	Silver	7440-22-4		0.236	mg	688047	2622
Die Attach Epoxy (Ablebond 8290)	Other inorganic materials	0.000	mg	supplier	Glue	Bisphenol F type epoxy resin	9003-36-5		0.059	mg	172012	656
Die Attach Epoxy (Ablebond 8290)	Other inorganic materials	0.000	mg	supplier	Glue	Gamma Butyrolactone	96-48-0		0.016	mg	46647	178
Die Attach Epoxy (Ablebond 8290)	Other inorganic materials	0.000	mg	supplier	Glue	Polyoxypropylenediamine	9046-10-0		0.016	mg	46647	178
Die Attach Epoxy (Ablebond 8290)	Other inorganic materials	0.000	mg	supplier	Glue	Proprietary Metal Oxide	Proprietary		0.016	mg	46647	178
Encapsulation	Other inorganic materials	40.879	mg	supplier	Molding compound	Silica fused	60676-86-0		35.170	mg	860344	390778
Encapsulation	Other inorganic materials	0.000	mg	supplier	Molding compound	Proprietary Epoxy resin A	Proprietary		1.241	mg	30358	13789
Encapsulation	Other inorganic materials	0.000	mg	supplier	Molding compound	Proprietary Epoxy resin B	25068-38-6		1.241	mg	30358	13789
Encapsulation	Other inorganic materials	0.000	mg	supplier	Molding compound	Proprietary Phenol resin A	Proprietary		1.241	mg	30358	13789
Encapsulation	Other inorganic materials	0.000	mg	supplier	Molding compound	Proprietary Phenol resin B	Proprietary		1.241	mg	30358	13789
Encapsulation	Other inorganic materials	0.000	mg	supplier	Molding compound	Proprietary Metal Hydroxide	21645-51-2		0.621	mg	15191	6900
Encapsulation	Other inorganic materials	0.000	mg	supplier	Molding compound	Carbon Black	1333-86-4		0.124	mg	3033	1378
Bonding Wire	Other inorganic materials	0.524	mg	supplier	Wire	Gold	7440-57-5		0.524	mg	1000000	5822
Leadframe	Other inorganic materials	44.261	mg	supplier	Alloy	Copper	7440-50-8		42.395	mg	957841	471056
Leadframe	Other inorganic materials	0.000	mg	supplier	Alloy	Silicon	7440-21-3		0.322	mg	7275	3578
Leadframe	Other inorganic materials	0.000	mg	supplier	Alloy	Magnesium	7439-95-4		0.078	mg	1762	867
Leadframe	Other inorganic materials	0.000	mg	supplier	Alloy	Silver	7440-22-4		0.044	mg	994	489
Leadframe	Other inorganic materials	0.000	mg	supplier	Nickel (external applications only)	Nickel	7440-02-0		1.422	mg	32128	15800
Finishing	Other inorganic materials	2.100	mg	supplier	Connection coating	Tin	7440-31-5		2.100	mg	1000000	23333